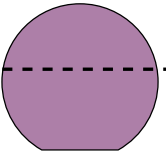

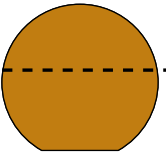


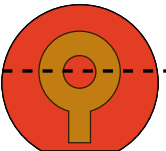

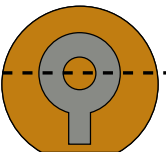
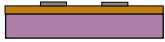
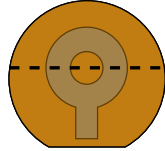
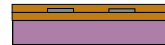
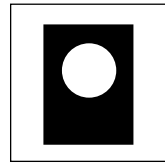
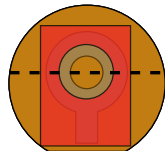
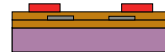
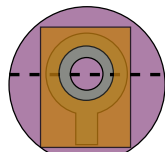
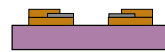


#	Mask	Result	X-section	Description
#1				Polished silicon wafer
#2				Spin coating of first layer of polyimide
#3				Spin coating of negative resist Patterning with Mask 1 (Metal)
#4				Evaporation of Platinum Lift-off

#	Mask	Result	X-section	Description
#5				Spin coating of second layer of polyimide
#6				Spin coating of positive resist Patterning of Mask 2 (PI)
#7				Reactive Ion Etching of PI Release by peeling